

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









## **DATASHEET**

# SMD ■ Technical Data Sheet EAHP5630RA0



### **Features**

- Top view LED
- High luminous flux output
- High current capability
- · White package
- Wide viewing angle
- Pb-free
- The product itself will remain within RoHS compliant version.
- Precondition: Bases on JEDEC J-STD 020D Level 3

### **Descriptions**

Due to the package design, EAHP5630RA0 has wide viewing angle This feature makes the LED ideal for light guide application.

### **Applications**

- Decorative and Entertainment Lighting.
- Light pipe application
- Indicator and backlight in office and family equipment
- General use



### **Device Selection Guide**

Chip Materials	Emitted Color	Resin Color
AlGalnP	Super Red	Water Clear

### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	$V_R$	12	V	
Forward Current	I <sub>F</sub>	150	mA	
Peak Forward Current (Duty 1/10 @1KHz)	I <sub>FP</sub>	300	mA	
Power Dissipation	Pd	500	mW	
Junction Temperature	T <sub>j</sub>	125	$^{\circ}\! \mathbb{C}$	
Operating Temperature	$T_{opr}$	-40 ~ +85	$^{\circ}\! \mathbb{C}$	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\! \mathbb{C}$	
The word Decistors	Rth <sub>J-A</sub>	150	K/W	
Thermal Resistance	Rth <sub>J-S</sub>	100	K/W	
ESD	ESD <sub>HBM</sub>	2000	V	
(Classification acc. AEC Q101)	ESD <sub>MM</sub>	200	V	
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260 $^{\circ}\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^{\circ}\mathbb{C}$ for 3 sec.		



### **Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	2850		5700	mcd	I <sub>F</sub> =150mA
Viewing Angle	$2\theta_{1/2}$		120		deg	I <sub>F</sub> =150mA
Peak Wavelength	λр		639		nm	I <sub>F</sub> =150mA
Dominant Wavelength	λd	620		632	nm	I <sub>F</sub> =150mA
Spectrum Radiation Bandwidth	Δλ		20		nm	I <sub>F</sub> =150mA
Forward Voltage	$V_{F}$	1.7		2.7	V	I <sub>F</sub> =150mA
Reverse Current	I <sub>R</sub>			10	μA	V <sub>R</sub> =12V

### Note:

- 1. Tolerance of Luminous Intensity: ±11%
- 2. Tolerance of Dominant Wavelength: ±1nm
- 3. Tolerance of Forward Voltage: ±0.1V

### Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
Y1	2850	3600		
Y2	3600	4500	mcd	$I_F = 150 \text{mA}$
Z01	4500	5700		·

Note:

Tolerance of Luminous Intensity: ±11%

### **Bin Range of Dominant Wavelength**

Bin Code	Min.	Max.	Unit	Condition
R1	620	624		
R2	624	628	nm	IF =150mA
R3	628	632	<u> </u>	

Note:

Tolerance of Dominant Wavelength: ±1nm



### **Bin Range of Forward Voltage**

Bin Code	Min.	Max.	Unit	Condition
B1	1.70	1.95		
B2	1.95	2.20		IF =150m A
B3	2.20	2.45	v	IF =150mA
B4	2.45	2.70		

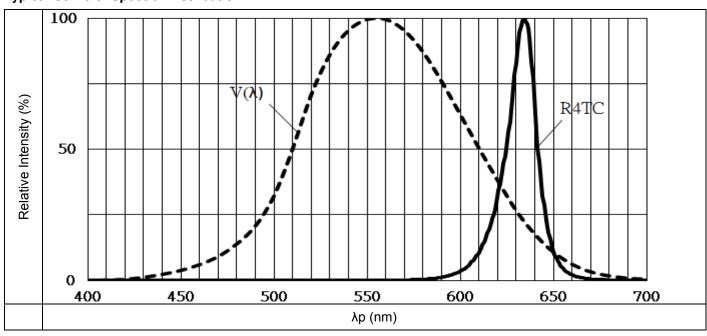
Note:

Tolerance of Forward Voltage: ±0.1V



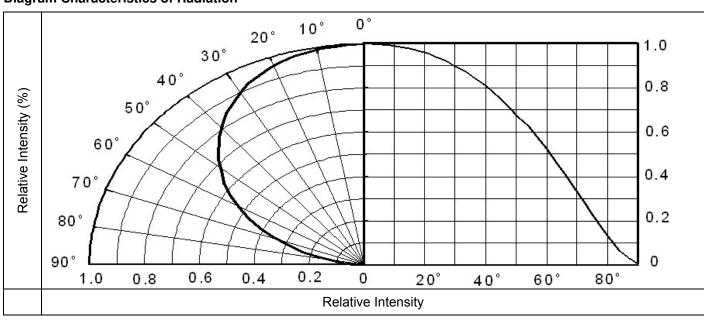
### **Typical Electro-Optical Characteristics Curves**

### **Typical Curve of Spectral Distribution**



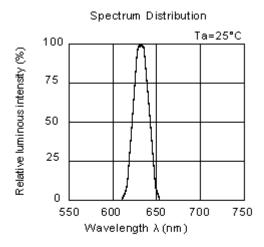
Note:  $V(\lambda)$ =Standard eye response curve;  $I_F$  =150mA

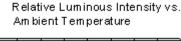
### **Diagram Characteristics of Radiation**

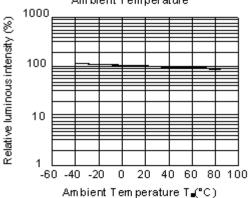




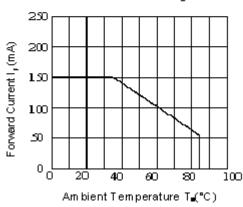
### **Typical Curve of Spectral Distribution**







### Forward Current Derating Curve



# Forward Current vs. Forward Voltage Ta=25°C (A) 10

2.4

0 L 1.6

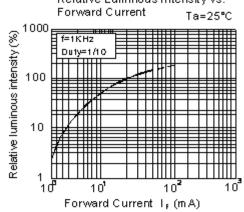
2.0

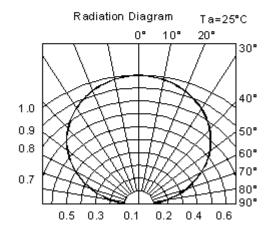
Forward Voltage  $V_{\mathfrak{p}}(V)$ Relative Luminous Intensity vs.

2.8

3.0

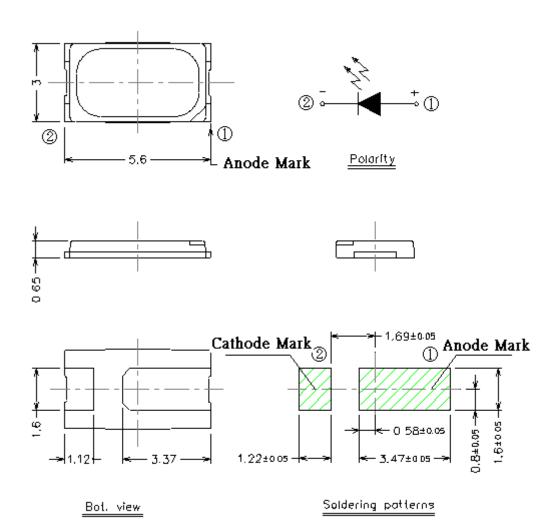
3.0







### **Package Dimension**

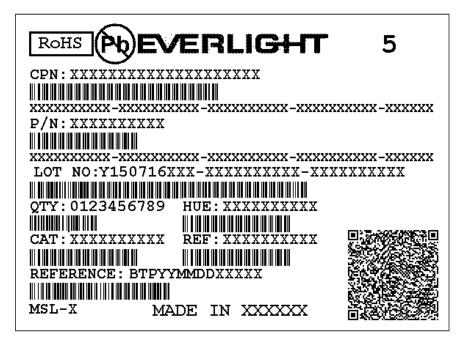


Note: Tolerances unless mentioned ±0.1mm. Unit = mm



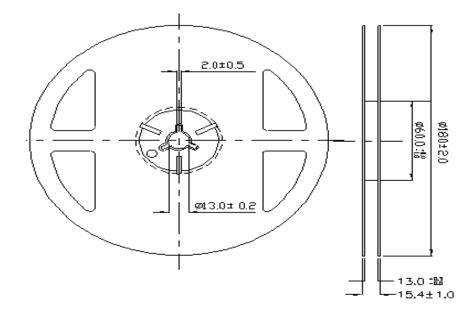
### **Moisture Resistant Packing Materials**

### **Label Explanation**



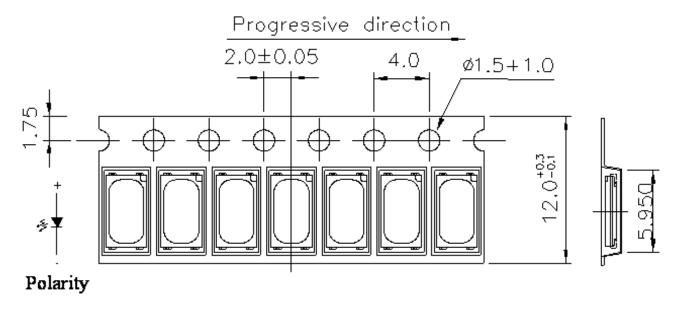
- · CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- · CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- · REF: Forward Voltage Rank
- · LOT No: Lot Number

### **Reel Dimensions**





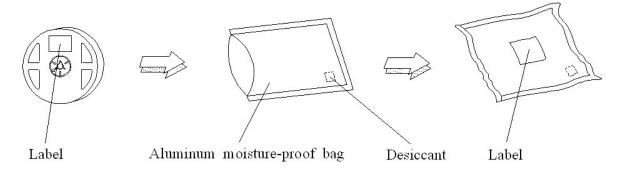
### Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note: Tolerances unless mentioned ±0.1mm. Unit = mm



### **Moisture Resistant Packing Process**

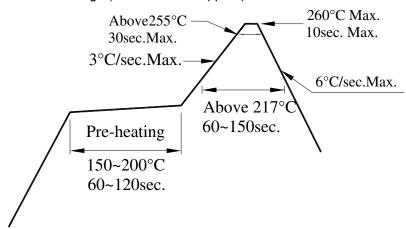


Note: Tolerances unless mentioned ±0.1mm. Unit = mm

### **Precautions for Use**

### 1. Over-current-proof

1.1 Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).



### 2. Storage

- 2.1 Don't open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 72Hrs under 30℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.baking treatment: 60±5°C for 24 hours

### 3. Soldering Condition

- 3.1 Pb-free solder temperature profile
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less



than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

### **Application Restrictions**

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

### **Revision History**

Rev.	Modified date	File modified contents
1	2014/12/04	New Spec
2	2015/06/30	Approved
3	2016/01/28	Correction Description